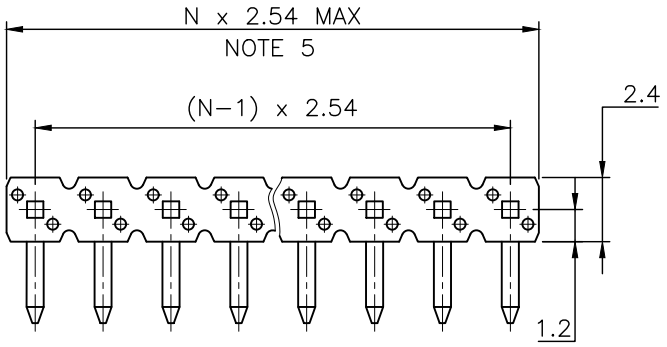
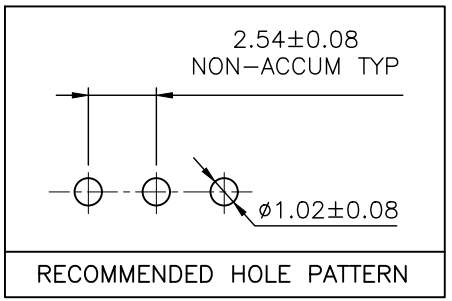
PRODUCT NUMBER

77315–YXX–XXLF

- RoHS COMPATIBLE SEE NOTE 7
- TOTAL NB OF POSITIONS 01 TO 36
- PACKAGING, NOTE 3
- PIN STYLE SEE SHEET 2
- PLATING SEE SHEET 2





RECOMMENDED HOLE PATTERN

NOTES:

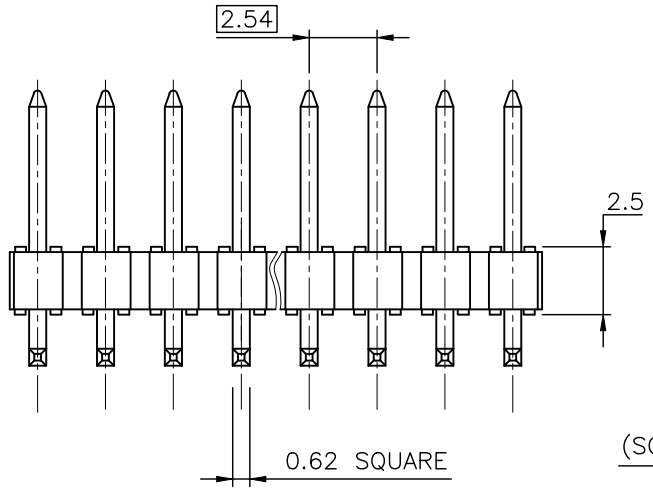
1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V–0 COLOR: BLACK
2. PIN MATERIAL : PHOSPHOR BRONZE
3. PACKAGING:
   – PACKAGING POLYBAG
   "V" BLIBOX PACK FOR CUSTOMER DEDICATED PART
   "K" TAPE & REEL PACKAGING WITHOUT PICK UP CAP
4. 9N MIN RETENTION IN EITHER DIRECTION
5. TO DETERMINE DIMENSIONS :
   N = NUMBER OF POSITIONS PER ROW
   EXAMPLE : 8 POS N x 2.54 = 20.32mm
6. UNDERPLATING : 1.27µm Ni MIN
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

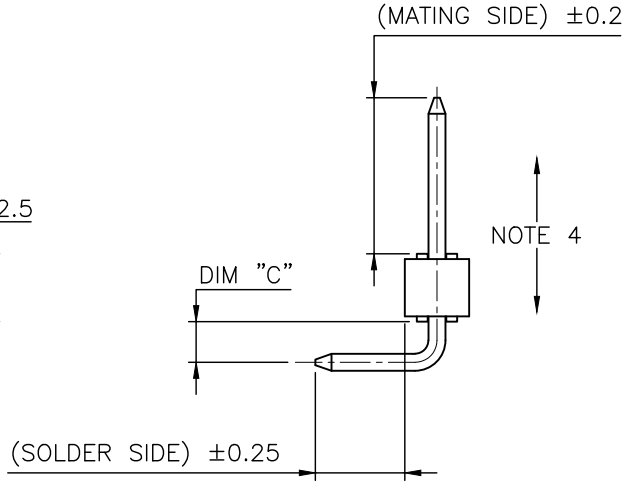
   a – PLATING:
   – "LF" MEANS THE PRODUCT IS LEAD–FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

   b – MANUFACTURING PROCESS COMPATIBILITY
   – THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
   – REFLOW COMPATIBLE

   c – LABELING:
   – MEETS PACKAGING SPECS AS PER GS–14–920

   d – LEGAL STATEMENT: SEE GS–47–0004





mat'l. code				surface		tolerance		projection	product family
SEE NOTES				ISO 1302		ISO 406 ISO 1101			BERGSTIK
ltr	ecn no	dr	date	tolerances unless otherwise specified					title
BB	F–26544	LMU	17.11.20	angles	linear	.X ±0.3			UNSHR.HEADER
BC	F–38749	DDE	20.10.26			.XX ±0.15		mm	RA SR TMT
						.XXX ±0.05		scale 5:1	
AW	F–23551	LMU	16.03.21	dr	D.LE	01.01.24			dwg no 77315 sheet 1 of 2 size A3
AX	F–24328	AMA	16.06.17	engr	JM.C	01.01.24			
AY	F–25336	DDE	16.11.15	chr	JM.C	01.01.24			
BA	F–25361	DDE	16.11.16	appd	JF.N	01.01.24			type CUSTOMER Drawing
sheet	revision	BC	6						
index	sheet	1	2						

PRODUCT SPECIFICATIONS			
PIN STYLE	MATING	SOLDER	DIM "C"
01	5.72	2.57	1.5
02	5.72	5.11	1.5
03	5.72	7.65	1.5
07	5.72	5.11	3.9
13	5.72	3.45	1.5
18	5.84	3.05	1.5
22	11.71	3.2	1.5
24	6.75	2.85	1.5
25	8.07	3.05	1.5
26	8.2	12.6	1.5
27	5	3.9	1.5
28	3.1	3.1	1.5
29	9.7	2.90	1.5
30	8.30	4.40	1.5
31	11.70	2.80	1.5
32	8.90	3.05	1.5
33	10.20	3.05	1.5
34	10.00	3.25	1.5
35	5.72	12.73	1.5
36	N/A		
37	N/A		
38	8.51	5.51	1.5
39	9.80	9.30	1.5
40	8.13	2.54	3.90
41	14.20	3.05	1.5
42	9.00	7.20	1.5
43	8.08	2.79	1.5
44	15.70	2.79	1.5
45	8.20	2.35	1.5
46	3.10	9.90	1.5
47	2.30	2.30	1.5
48	3.50	3.05	1.5
49	6.60	4.52	1.5
50	7.00	9.00	4.46
51	7.60	10.50	1.5

PRODUCT SPECIFICATIONS			
PIN STYLE	MATING	SOLDER	DIM "C"
52	2.54	3.05	1.5
53	1.2	2.30	1.5
54	2.5	7.40	2.66
55	5.1	5.1	1.5
56	3.0	5.83	3.4

PLATING

1 = 0.76µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAIL

4 = 3µm–5µm TIN FULL PLATED REFLOW

5 = 0.25µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAIL

8 = 0.38µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAIL

G = 0.76µm FULL GXT

S = 0.38µm FULL GXT

– 1.27µm NICKEL MIN UNDERLAYER FOR ALL PLATING VERSIONS

mat'l. code: SEE NOTES				surface ISO 1302		tolerance ISO 406 ISO 1101		projection	product family: BERGSTIK		
ltr	ecn no	dr	date	tolerances unless otherwise specified					title: UNSHR.HEADER RA SR TMT		
AP	F-23462	LMU	16.03.07	angles	linear	.X ±0.3		mm			
AR	F-23551	LMU	16.03.21			.XX ±0.15					
AS	F-24328	AMA	16.06.17			.XXX ±0.05		scale 5:1			
AT	F-25336	DDE	16.11.15	dr	D.LE	01.01.24			dwg no: 77315	sheet 2 of 2	size: A3
AU	F-25361	DDE	16.11..16	engr	JM.C	01.01.24					
AV	F-26544	LMU	17.11.20	chr	JM.C	01.01.24			type: CUSTOMER		Drawing
AW	F-38749	DDE	20.10.26	appd	JF.N	01.01.24					
sheet index	revision sheet										